ABSTRACT

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The present invention relates to a substrate holding apparatus for holding a substrate (W) such as a semiconductor wafer in a polishing apparatus for polishing the substrate to a flat finish. A substrate holding apparatus according to the present invention comprises a top ring body (2) having a receiving space therein, and a vertically movable member (206) which is vertically movable within the receiving space in the top ring body. An abutment member (209) having an elastic membrane is attached to a lower surface of the vertically movable member. The elastic membrane (291) of the abutment member comprises an abutment portion (291b), having a flange (291a) projecting outwardly, brought into direct or indirect contact with the substrate, and a connecting portion (291c) extending upwardly from a base portion (291d) of the flange of the abutment portion and being connected to the vertically movable member. The connecting portion is made of a material having a flexibility higher than the abutment portion.

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